

LCM Specification

Preliminary specification

Final Specification

Project No. 项目编号	TFT-H028B7QVTST3N40		
Customer 客户名称			
Module No. 客户型号			
Product type 产品内容	TFT LCD Module 240 x 3RGB x 320 Dots 2.8" TFT LCD		
Signature by customer: 客户确认签章:			
<input type="checkbox"/> Trial production <input type="checkbox"/> Mass production			
编 制	电子审核	结构审核	批 准
Y. L			

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Shenzhen Hot Display Technology Co., Ltd

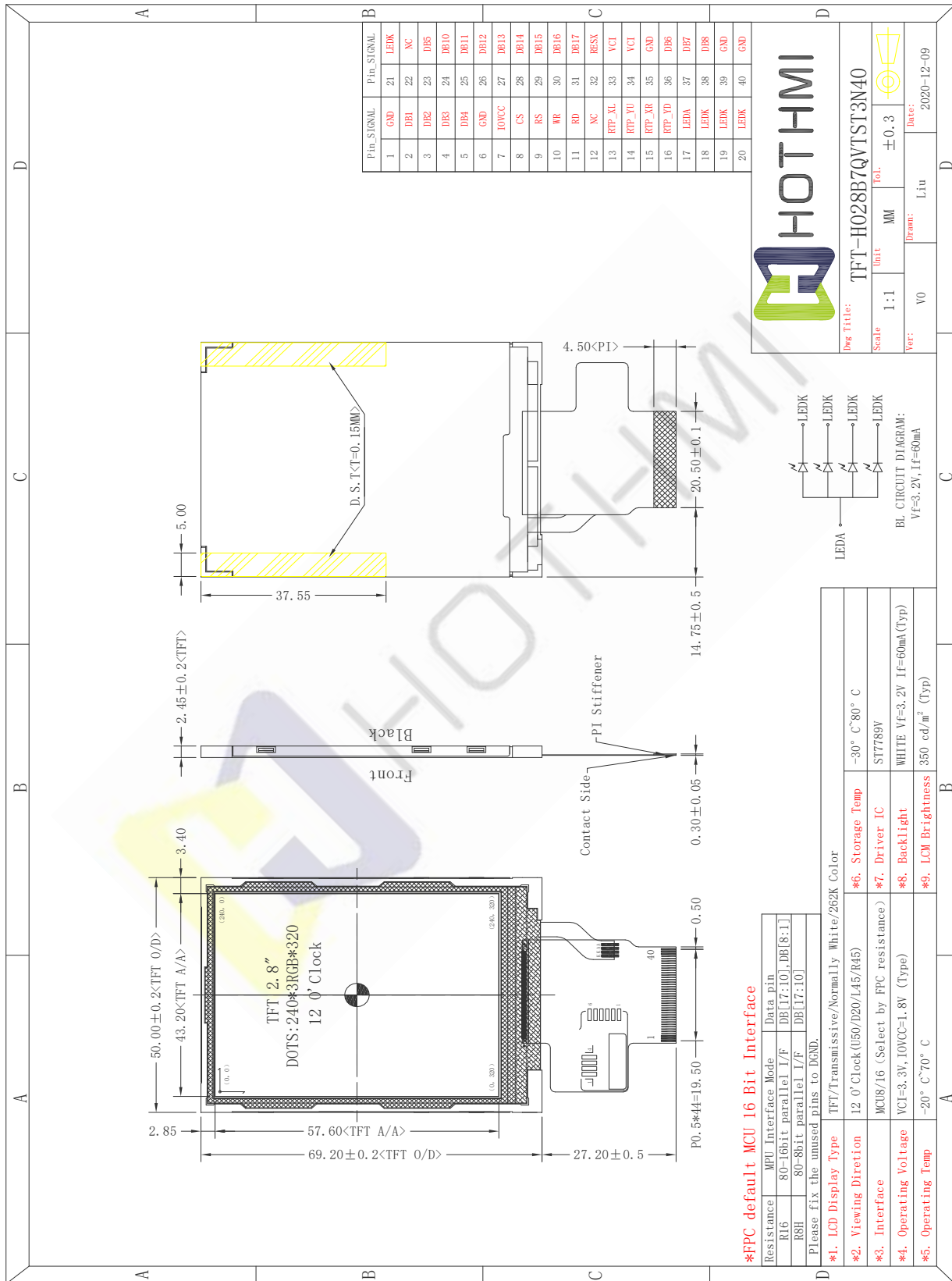
1 Document revision history :

DOCUMENT REVISION	DATE	DESCRIPTION	PREPARED BY	APPROVED BY
0	2020-12-18	First Release.	Y.L	

1. General Feature:

Item	Standard Value	Unit
Display Size	2.8"	--
Number of Pixels	240(H)x3(RGB)*320(V)	--
Active Area	43.20(H) *57.60(V)	mm
LCM Outline Dimension	50.00(H) ×69.20(V)× 2.45(D)	mm
Viewing Direction	12 O'clock	-
LCM Interface	Parallel 8080-series MCU8/16	-
LCM Driver IC	ST7789V	-
LCM Driver Voltage	VCI=2.8V (Max 3.3V)	V
Backlight	White LED	-
Touch Panel	Without Touch Panel	-
CTP Driver IC	---	-
CTP Driver Voltage	VDD=2.8V (Max 3.6V)	V
CTP I/O Digital Voltage	IOVDD=2.8V (Max 3.6V)	V
Operation Temperature	-20~70	°C
Storage Temperature	-30~80	°C

2. Outline Dimensions

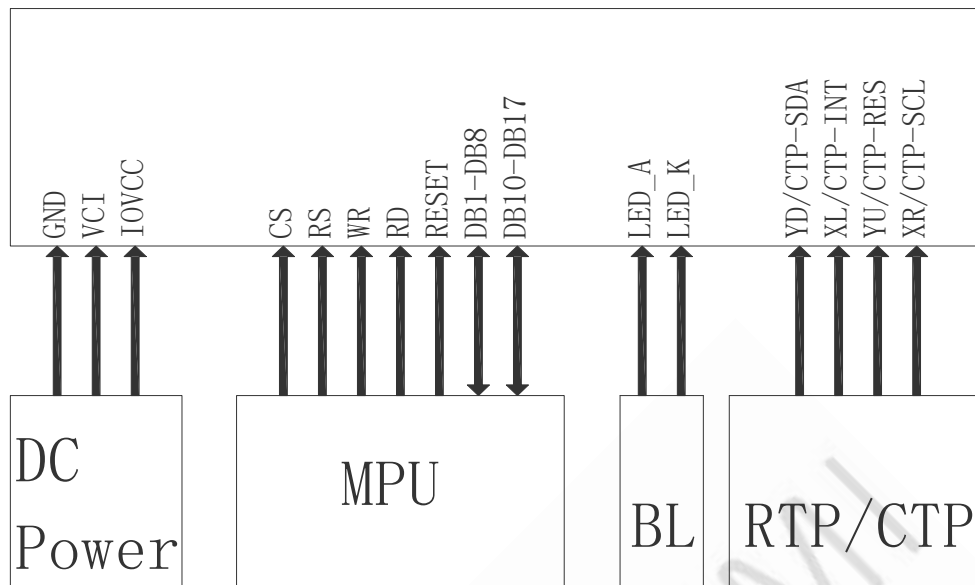


3. Pin Description

3.1 Pin Description

Pin NO.	Symbol	Description
1	GND	System Ground
2-5	DB1-4	Data Bus. If not used, please fix this pin at GND.
6	GND	System Ground
7	IOVCC	Power Supply for I/O System(1.65 ~ 3.3 V)
8	CS	Chip select input pin ("Low" enable).
9	RS	Display data/command selection pin in parallel IF.
10	WR	Write enable in MCU parallel interface
11	RD	Read enable in 8080 MCU parallel IF.
12	NC	This pin open.
13	XL/CTP_INT	RTP XL Position Input/CTP_External interrupt to the host.
14	YU/CTP_RES	RTP YU Position Input/CTP Reset Pin.
15	XR/CTP_SCL	RTP XR Position Input/CTP Serial clock signal.
16	YD/CTP_SDA	RTP YD Position Input/CTP Serial data input signal.
17	LEDA	LED Anode
18-21	LEDK	LED Cathode
22	NC	This pin open.
23	DB5	Data Bus. If not used, please fix this pin at GND.
24-31	DB10-17	Data Bus.
32	RESX	TFT Reset Pin.
33, 34	VCI	Analog Power (2.65 ~ 3.3 V)
35	GND	System Ground
36-38	DB6-8	Data Bus. If not used, please fix this pin at GND.
39-40	GND	System Ground
- END -		

3.2 Wiring Diagram



*Interface definition by Resistance

Resistance	MPU Interface Mode	Data pin
R16	80-16bit parallel I/F	DB[17:10], DB[8:1]
R8H	80-8bit parallel I/F	DB[17:10]

Please fix the unused pins to DGND.

***FPC default MCU 16 Bit Interface**

4. Electrical Characteristics

4-1 TFT LCD Module Operating Conditions

Item	Symbol	Condition	Min	Type	Max	Unit
Interface logic circuits	IOVCC	-	1.65	1.80	3.30	V
Analog Power supply	VCI	-	2.50	2.80	3.30	V
TFT Gate on voltage	VGH	-	10.0	-	16.0	V
TFT Gate off voltage	VGL	-	-16.0	-	-10.0	V

4-2 LED back light specification (pera chip)

Item	Symbol	Condition	Min	Type	Max	Unit
Forward voltage	Vt	If=20mA	-	3.2	-	V
Forward current	Ipn	/1-chip	-	60	-	mA
Luminance(With LCD)	Lv	If=60mA	-	350	-	cd/m ²
Luminous color	White					

4-3 CTP Operating Conditions

Item	Symbol	Condition	Min	Type	Max	Unit
Power Supply Voltages	VDD	-	2.8	3.30	3.60	V
I/O Digital Voltage	IOVDD	-	2.8	3.30	3.60	V
Operating Temperature	Topr	-	-20	-	70	°C
Storage Temperature	Tstg	-	-30	-	80	°C

5. OPTICAL SPECIFICATION

4.1 Overview

The test of Optical specifications shall be measured in a dark room (ambient luminance 1lux and temperature = 25 ± 2°C) with the equipment of Luminance meter system (Goniometer system and TOPCON BM-5) and test unit shall be located at an approximate distance 50cm from the LCD surface at a viewing angle of θ and Φ equal to 0°. The center of the measuring spot on the Display surface shall stay fixed. The backlight should be operating for 30 minutes prior to measurement.

4.2 Optical Specifications

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit	Remark
Viewing Angle Range	Horizontal	Θ L	CR>10	-	45	-	Deg.	Note 1
		Θ R		-	45	-	Deg.	
	Vertical	Θ U		-	50	-	Deg.	
		Θ D		-	20	-	Deg.	
Contrast ratio		CR	$\Theta = 0^\circ$	-	500	-		Note2
Color Gamut		CG		-	55	-	%	
White Chromaticity		Wx		-	0.301	-		
		Wy		-	0.337	-		
Reproduction of color	Red	Rx	$\Theta = 0^\circ$	-	0.621	-		Note4 (Based on C Light)
		Ry		-	0.332	-		
	Green	Gx		-	0.294	-		
		Gy		-	0.577	-		
	Blue	Bx		-	0.141	-		
		By		-	0.157	-		
Response Time (Rising + Falling)		Tr+Tf	$\Theta = 0^\circ$ Ta= 25°C	-	16	-	ms	Note5
Transmittance		Tr		-	-	-	%	Note3

Note:

1. Viewing angle is the angle at which the contrast ratio is greater than 10. The viewing angles are determined for the horizontal or 3, 9 o' clock direction and the vertical or 6, 12 o' clock direction with respect to the optical axis which is normal to the LCD surface (see FIGURE 1).

2. Contrast measurements shall be made at viewing angle of $\Theta = 0$ and at the center of the LCD surface. Luminance shall be measured with all pixels in the view field set first to white, then to the dark (black)

state . (see FIGUR 1) Luminance Contrast Ratio (CR) is defined mathematically.

$$CR = \frac{\text{Luminance when displaying a white raster}}{\text{Luminance when displaying a black raster}}$$

3. Transmittance is the Value without APF and without CG.

4. The color chromaticity coordinates specified in the above table shall be calculated from the spectral data measured with all pixels first in red, green, blue and white. Measurements shall be made at the center of the panel.

5. The electro-optical response time measurements shall be made as FIGURE 2 by switching the “data” input signal ON and OFF. The times needed for the luminance to change from 10% to 90% is T_r , and 90% to 10% is T_f .

Figure1 Measurement Set Up

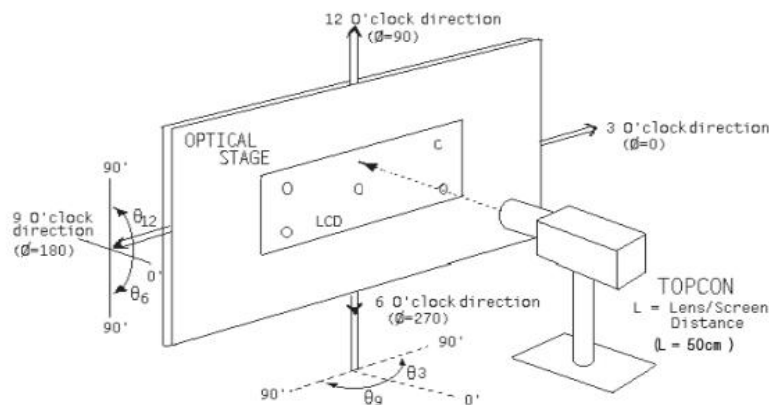
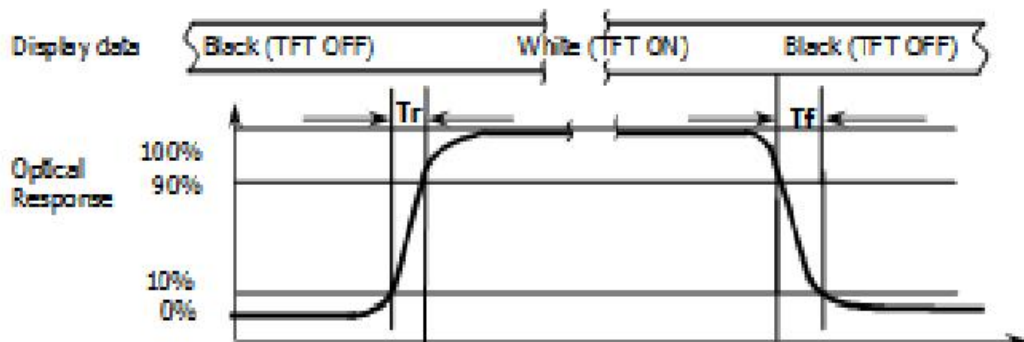
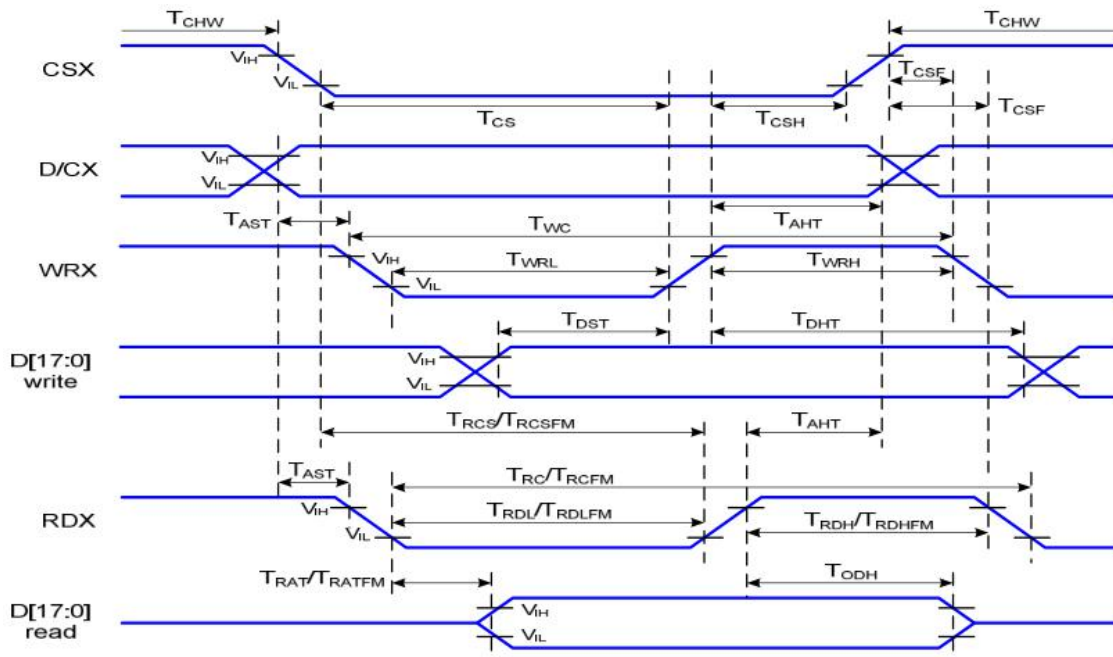


Figure2 Response Time Testing



6. Timing Characteristics of Input Signals

6-1 8080 Series MCU Parallel Interface Characteristics: 16/8-bit Bus



VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25°C

Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	T _{AST}	Address setup time	0		ns	-
	T _{AHT}	Address hold time (Write/Read)	10		ns	
CSX	T _{CHW}	Chip select "H" pulse width	0		ns	-
	T _{CS}	Chip select setup time (Write)	15		ns	
	T _{RCS}	Chip select setup time (Read ID)	45		ns	
	T _{RCSFM}	Chip select setup time (Read FM)	355		ns	
	T _{CSF}	Chip select wait time (Write/Read)	10		ns	
	T _{CSH}	Chip select hold time	10		ns	
WRX	T _{WC}	Write cycle	66		ns	-
	T _{WRH}	Control pulse "H" duration	15		ns	
	T _{WRL}	Control pulse "L" duration	15		ns	
RDX (ID)	T _{RC}	Read cycle (ID)	160		ns	When read ID data
	T _{RDH}	Control pulse "H" duration (ID)	90		ns	
	T _{RDL}	Control pulse "L" duration (ID)	45		ns	
RDX (FM)	T _{RCFM}	Read cycle (FM)	450		ns	When read from frame memory
	T _{RDHFM}	Control pulse "H" duration (FM)	90		ns	
	T _{RDLFM}	Control pulse "L" duration (FM)	355		ns	
D[17:0]	T _{DST}	Data setup time	10		ns	For CL=30pF
	T _{DHT}	Data hold time	10		ns	
	T _{RAT}	Read access time (ID)		40	ns	
	T _{RATFM}	Read access time (FM)		340	ns	
	T _{ODH}	Output disable time	20	80	ns	

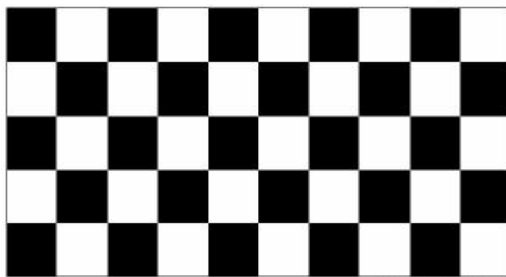
7. RELIABILITY TEST

7-1 Temperature and Humidity

TEST ITEMS	CONDITIONS	NOTE
High Temperature Operation	60°C ; 120hrs	
High Temperature Storage	70°C ; 120hrs	
High Temperature High Humidity Operation	60°C; 90%RH ; 120hrs (No condensation)	
Low Temperature Operation	-10°C ; 120hrs	
Low Temperature Storage	-20°C ; 120hrs	
Thermal Shock	-30°C (0.5hr) ~ 80°C (0.5hr) ; 100 Cycles	Non-Operating
Image Sticking	25°C ; 2hrs	1

Note 1: Condition of Image Sticking test: 25°C ±2°C

Operation with test pattern sustained for 4 hrs, then change to gray pattern immediately. After 5 mins, the mura must be disappeared completely .



(a) Test Pattern (chess board Pattern)



(b) Gray Pattern

7-2 Shock and Vibration

ITEMS	CONDITIONS
Packing Shock (Non-Operation)	<ul style="list-style-type: none"> ● Shock level:980m/s² ● Waveform:1/2 Sine wave,6msec ● ±X, ±Y ±Z,each axis 1 times
Packing Vibration (Non-Operation)	<ul style="list-style-type: none"> ● Frequency range:8-33.3HZ ● Stoke:1.0mm ● Sweep: 10Hz-50Hz ● x,y,z 2 hours for each direction

7-3 Electrostatic Discharge

TEST ITEM	CONDITIONS
ESD (Non-operation)	150pF,330Ω , Contact±4KV,Air :±8KV.Note 1
	200pF,0Ω , ±200V Contact test.Note 2

Note:Measure Point:

- 1.LCD glass and metal bezel
- 2.IF connector pins

8. HANDLING & CAUTIONS

8-1 Caution For Operation

◆ Since the LCM is made of glass, do not apply strong mechanical impact or static load onto it. Handling with care since shock, vibration, and careless handling may seriously affect the product. If it falls from a high place or receives a strong shock, the glass may be broken.

◆ It is indispensable to drive the LCM within the specified voltage limit since the higher voltage than the limit causes LCM's life shorter. An electro-chemical reaction due to DC causes undesirable deterioration of the LCM so that the use of DC drive should be avoided.

◆ Do not connect or disconnect the LCM to or from the system when power is on.

◆ Never use the LCM under abnormal conditions of high temperature and high humidity.

◆ When exposed to drastic fluctuation of temperature (hot to cold or cold to hot), the LCM may be affected; specifically, drastic temperature fluctuation from cold to hot, produces dew on the LCM's surface which may affect the operation of the polarizer on the LCM.

◆ Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand LCM may turn black at temperature above its operational range. However those phenomena do not mean malfunction or out of order with the LCM. The LCM will revert to normal operation once the temperature returns to the recommended temperature range for normal operation.

◆ Do not display the fixed pattern for a long time when using a normally black panel, as it may cause image sticking due to the LCM structure. If the screen is displayed in fixed mode, use a screen saver. It is recommended to display the fixed mode in less than 2 minutes or less.

◆ Do not disassemble and/or re-assemble LCM module

7-2 Caution Against Static Charge

◆ The LCM uses C-MOS LSI drivers, so customers are recommended that any unused input terminal would be connected to V_{DD} or V_{SS}, do not input any signals before power is turned on, and ground your body, work/assembly area, assembly equipments to protect against static electricity.

◆ Remove the protective film slowly, keeping the removing direction approximate 30-degree not vertical from panel surface, if possible, under ESD control device like ion blower, and the humidity of working room should be kept over 50%RH to reduce the risk of static charge.

◆ Avoid the use of work clothing made of synthetic fibers. We recommend cotton clothing or other conductivity-treated fibers.

◆ In handling the LCM, wear non-charged material gloves. And the conducting wrist to the earth and the conducting shoes to the earth are necessary

9. LCD display initialization code

```

Void Panel_Initial_code(void)
{
//-----//
WriteComm(0x11);
Delay(120); //Delay 120ms
//-----Display Setting-----//
WriteComm(0x36); //Memory Data Access Control,See IC specifications P125,P215
WriteData(0x00);
WriteComm(0x3A); //Interface Pixel Format,See IC Sspecifications PEC P224
WriteData(0x55);
//-----Frame rate setting-----//
WriteComm(0xb2);
WriteData(0x0c);
WriteData(0x0c);
WriteData(0x00);
WriteData(0x33);
WriteData(0x33);
WriteComm(0xb7);
WriteData(0x35);
//-----Power setting-----//
WriteComm(0xbb);
WriteData(0x2b);
WriteComm(0xc0);
WriteData(0x2c);
WriteComm(0xc2);
WriteData(0x01);
WriteComm(0xc3);
WriteData(0x11);
WriteComm(0xc4);
WriteData(0x20);
WriteComm(0xc6);
WriteData(0x0f);
WriteComm(0xd0);
WriteData(0xa4);
WriteData(0xa1);
//-----gamma setting-----//
WriteComm(0xe0);
WriteData(0xd0);

```

```
WriteData(0x00);  
WriteData(0x05);  
WriteData(0x0e);  
WriteData(0x15);  
WriteData(0x0d);  
WriteData(0x37);  
WriteData(0x43);  
WriteData(0x47);  
WriteData(0x09);  
WriteData(0x15);  
WriteData(0x12);  
WriteData(0x16);  
WriteData(0x19);  
WriteComm(0xe1);  
WriteData(0xd0);  
WriteData(0x00);  
WriteData(0x05);  
WriteData(0x0d);  
WriteData(0x0c);  
WriteData(0x06);  
WriteData(0x2d);  
WriteData(0x44);  
WriteData(0x40);  
WriteData(0x0e);  
WriteData(0x1c);  
WriteData(0x18);  
WriteData(0x16);  
WriteData(0x19);  
Delay(120);  
WriteComm(0x29);  
Delay(120);  
}
```

```

#define ROW  320    // Y
#define COL  240    // X
void BlockWrite(unsigned int Xstart,unsigned int Xend,unsigned int Ystart,unsigned int Yend)
{
    WriteComm(0x2a);
    WriteData(Xstart>>8);
    WriteData(Xstart&0xff);
    WriteData(Xend>>8);
    WriteData(Xend&0xff);

    WriteComm(0x2b);
    WriteData(Ystart>>8);
    WriteData(Ystart&0xff);
    WriteData(Yend>>8);
    WriteData(Yend&0xff);

    WriteComm(0x2c);
}
void DispColor(unsigned int color)    //MCU 16 Bit
{
    unsigned int i,j;
    BlockWrite(0,COL-1,0,ROW-1);
    CS0=0;
    RS=1;
    RD0=1;
    DBH=color>>8;
    DBL=color;
    for(i=0;i<ROW;i++)
    {
        for(j=0;j<COL;j++)
        {
            WR0=0;
            WR0=1;
        }
    }
    CS0=1;
}

```



```
Void Panel_SleepIn_Mode (void)
{
Write command 0x10;
Delays (120);
}
Void Panel_SleepOut_Mode (void)
{
Write command 0x11;
Delays (120);
}
```

- END -